

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"US 20060257575"	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 14:53
L3	76	ink with (epoxyacrylate or polyesteretraacrylate or urethanacrylate or diacrylate oligomer or benzildimethylketal)	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:26
L4	30	ink with (epoxyacrylate or polyesteretraacrylate or urethanacrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004"	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:26
L5	190	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004"	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:29
L6	104	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004" and UV	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:29
L7	58	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004" and UV cur\$4	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:29
L8	7	topcoat\$4 with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004"	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:30
L9	18	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004" and UV cur\$4 and metal\$5 with substrate	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:35
L10	2	"20030124339".pn.	US-PGRUB; USPAT; USCOR; DERWENT	ADJ	ON	2011/10/20 15:42
S1	1	("6548121").PN.	USPAT; USCOR	OR	OFF	2009/02/19 16:58
S2	1180	"ciba specialty chemicals corporation".as.	US-PGRUB; USPAT; FFRS; EPC; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:03

S3	5	"ciba specialty chemicals corporation" as, and strongly adherent coatings	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S4	5	"ciba specialty chemicals corporation" as, and strongly adherent coating	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S5	1	10/566743.app.	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
S6	1	("7455891").PN.	{USPAT; USCOR	OR	OFF	2009/02/20 11:00
S7	8	("7455891" or ("6251963" or ("6486228" or ("6515051" or ("6803392" or ("6733847" or ("6548121" or ("6368362"))).PN.	{USPAT; USCOR	OR	OFF	2009/02/20 11:09
S8	9	("7455891" or ("6251963" or ("6486228" or ("6515051" or ("6803392" or ("6733847" or ("6548121" or ("6368362" or ("6399805"))).PN.	{USPAT; USCOR	OR	OFF	2009/02/20 11:14
S9	108	"3669951" "3936305" "4082679" "4199421" "4226763" "4246315" "4275004" "4278589" "4292152" "4298738" "4315848" "4324744" "4347180" "4385109" "4466993" "4533652" "4567106" "4681905" "4684679" "4684680" "4710523" "4737593" "4792632" "4861916" "4868246" "4965294" "4990364" "5053246" "5080994" "5106891" "5108835" "5116534" "5153284" "5166355" "5168087" "5196142" "5218009" "5250698" "5252403" "5278314" "5280124" "5292890" "5330539" "5380850" "5399770" "5436349" "5456728" "5472992" "5504236" "5516914" "5549847" "5554760" "5563242" "5574166" "5607987" "5646088" "5935900" "5942290" "5955514" "5990189" "6099122" "6190423" "6329445" "6344505" "6361925" "6376065" "6399805" "6407254" "6548121" "6733847".PN. OR ("6251963" "6368362" "6399805" "6486228" "6515051" "6548121" "6733847" "6803392" "7455891").UPFN.	{US-PGRUB; USPAT; USCOR	ADJ	ON	2009/02/20 11:21
S10	15	("4199421" "4246315" "4466993" "4567106" "4990364" "5053246" "5252403" "6099122" "6548121" "6733847").PN. OR ("6548121" "6733847" "7455891").UPFN.	{US-PGRUB; USPAT; USCOR	ADJ	ON	2009/02/20 11:22
S11	21169	427,533,535,536,517,407,1-412,5,532-559,517,509,512,513,517,518,519,520,535,536,538,551,553,554,556,407,2,409,412,412,1,419,2.ccls. or 430/311.ccls.	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S12	5299	427/533,509.ccls. or 430/311.ccls.	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S13	211	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S14	139	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY<"2004"	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30

S15	13	(adhere\$4 or adhesion or glu\$3 or bond\$3) with metallized with (organic or polymer) with substrate and @PY<"2004" and S11	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S16	7	circuit and photoinitiator with adhesion with metal	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
S17	183	circuit and photoinitiator with adhesion and (metal or copper)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S18	13	circuit and photoinitiator with adhesion with (metal or copper)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S19	613	circuit and photoresist with adhesion with (metal or copper)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S20	283	circuit and photoresist with adhesion with (metal or copper) and plasma	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S21	47	circuit and photoresist with adhesion with (metal or copper) with plasma	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19
S22	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion with (metal or copper) with plasma	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S23	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) and adhesion with (metal or copper) with plasma	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35

S25	46	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink\$3 or UV) with adhesion	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
S27	2	"20030129322" did.	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
S28	13	solder mask with (cvd or evaporate or pvd)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
S29	692	solder with (cvd or evaporate or pvd)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
S30	5	solder with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
S31	149	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S32	12645	metal with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist)	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S33	45	solder with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S34	580	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57

S35	25	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S36	3	wiring board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
S37	121	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizable or UV or photoinitiator or photoresist) and @PY<"2004" and cmp	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
S38	1	("6524950").PN	USPAT; USCOR	OR	OFF	2009/02/20 19:21
S39	800	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S40	189	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S41	12	photoresist with (lift off or liftoff) and polymer\$2 with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
S42	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2003"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S43	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 with (solvent or mechanical\$3) and dry with (oven or IR or hot gas\$2 or microwave or roller) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S44	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop\$3 and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S45	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or metal\$3 or glass or metal oxide) with substrate and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42

S46	132	(lithography or photoresist) with (lift off or liftoff) and (polymer\$2 or meta\$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/02/23 13:43
S47	265	427/98.5.ods.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/02/23 14:01
S48	95	427/98.5.ods. and (resist or photoinitiator)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/02/23 14:02
S49	26	427/98.5.ods. and (resist or photoinitiator) and plasma	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/02/23 14:03
S50	2	10/502206.app.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/02/23 15:36
S51	2	"5320933".pn.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/09/27 14:15
S52	18699	"circuit board" with ceramic	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/09/27 14:34
S53	267	"circuit board" with ceramic with metallized	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/09/27 14:35
S54	96	"circuit board" with ceramic with metallized) ab.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/09/27 14:35
S55	59	"circuit board" with ceramic with metallized) ab. and @PY<"2004"	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; BM_TOB	ADJ	ON	2009/09/27 14:35

S57	1273	cur\$3 with (\$radiation or \$radiated radiation or UV or ultraviolet or ultra violet) with primer	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 17:32
S58	29	cur\$3 with (\$radiation or \$radiated radiation or UV or ultraviolet or ultra violet) with primer with plasma	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 17:32
S59	2	"US 20070245956"	{US-PGRUB; USPAT; USOCR; DERWENT	ADJ	ON	2009/09/28 10:46
S60	73514	{adhere\$4 or adhesion or glu\$3 or bond\$3 or prime\$1} with meta\$6 with substrate	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/18 16:24
S61	274	{adhere\$4 or adhesion or glu\$3 or bond\$3 or prime\$1} with meta\$6 with photoinitiator	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/18 16:25
S62	127	{adhere\$4 or adhesion or glu\$3 or bond\$3 or prime\$1} with meta\$6 with photoinitiator and @PY<:"2004"	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/18 16:26
S63	1	wo-0158971-A2.dld.	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/27 15:47
S64	2	"20040011288".pn.	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/27 16:15
S65	1	("7112351").PNL	{USPAT; USOCR	OR	OFF	2011/02/02 13:58
S66	1	("4233130").PNL	{USPAT; USOCR	OR	OFF	2011/02/02 14:02
S67	1	("6797428").PNL	{USPAT; USOCR	OR	OFF	2011/04/22 16:02
S68	64	{adhere\$4 or adhesion or glu\$3 or bond\$3 or prime\$1} with polymer\$2 with layers with photoinitiator and meta\$6 with substrate	{US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:39

S69	0	(adhere\$4 or adhesion or glu\$3 or bond\$3 or prime\$1) with polymer\$2 with layers with photoinitiator and metalized polymer with substrate	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:40
S70	0	polymer\$2 with layers with photoinitiator and metalized polymer with substrate	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:40
S71	29	polymer\$2 with layers with photoinitiator and metalized with substrate	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:40
S72	382	427/511.cds.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 12:24
S73	128	427/511.cds. and metal\$6 with (substrate or surface)	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 12:25
S74	2319	427/409-410.cds.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 12:31
S75	403	metal with primer with ink	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 17:30
S76	131	metal\$3 with substrate with primer with ink	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 17:31
S77	15	metal\$3 with substrate with primer with ink and photoinitiator	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 17:33
S78	2	*20020183413*.pn.	US-PGRUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/20 13:21

EAST Search History (Interference)

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